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(71) Applicant (for all designated States except US): **SILVERBROOK RESEARCH PTY LTD** [AU/AU]; 393 Darling Street, Balmain, NSW 2041 (AU).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **SILVERBROOK, Kia** [AU/AU]; Silverbrook Research Pty Ltd, 393 Darling Street, Balmain, NSW 2041 (AU).

(74) Agent: **SILVERBROOK, Kia**; Silverbrook Research Pty Ltd, 393 Darling Street, Balmain, NSW 2041 (AU).

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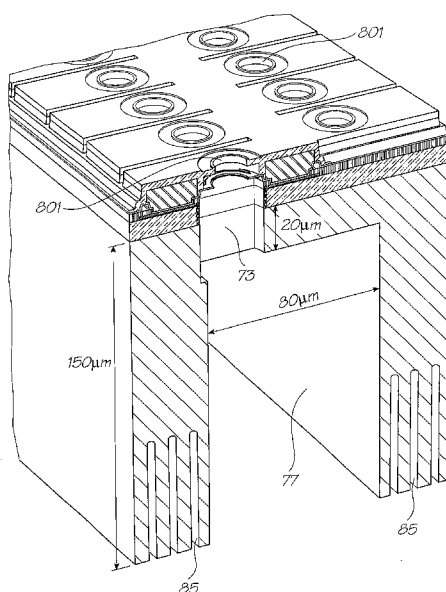
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(54) Title: METHOD OF BONDING SUBSTRATES



(57) Abstract: A method of bonding a first substrate to a second substrate is provided. The method comprises the steps of: (a) providing a first substrate having a plurality of etched trenches defined in a first bonding surface; (b) providing a second substrate having a second bonding surface; and (c) bonding the first bonding surface and the second bonding surface together using an adhesive. During bonding, the adhesive is received, at least partially, in the plurality of etched trenches, thereby increasing the adhesive bond strength whilst avoiding surface roughening. The method is particularly suitable for bonding semiconductor chips using liquid adhesives.

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